# 100% Material Declaration Data Sheet FT256



## Average Weight: 1.0494 g

| Component | Substance Description | CAS# or Description | % of Component | Use in Product | Component Weight/ Substance Weight (in grams) | Component % of Total |
|---|---|---|---|---|---|---|
| **Silicon Die** | | | | | **0.0596** | **5.68%** |
| | Silicon | 7440-21-3 | 100.00 | | 0.0596 | |
| **Die Attach Material** | | | | | **0.0062** | **0.59%** |
| | Silver | 7440-22-4 | 78.00 | | 0.0048 | |
| | Resin | Trade Secret | 22.00 | | 0.0014 | |
| **Mold Compound** | | | | | **0.5044** | **48.07%** |
| | Epoxy Resins | Trade Secret | 12.00 | | 0.0605 | |
| | SiO2 | 60676-86-0 | 88.00 | Filler | 0.4439 | |
| **Laminate** | | | | | **0.2008** | **19.14%** |
| | Laminate | Trade Secret | 63.35 | | 0.1272 | |
| | Solder Mask | Trade Secret | 14.39 | | 0.0289 | |
| | Copper | 7440-50-8 | 16.62 | Metal Layer | 0.0334 | |
| | Nickel | 7440-02-0 | 4.80 | Metal Layer | 0.0097 | |
| | Gold | 7440-57-5 | 0.84 | Metal Layer | 0.0017 | |
| **Bond Wire** | | | | | **0.0075** | **0.71%** |
| | Gold | 7440-57-5 | 99.00 | | 0.007436479 | |
| | Silver | 7440-22-4 | 0.0025 | | 0.000000188 | |
| | Copper | 7440-50-8 | 0.0005 | | 0.00000038 | |
| | Iron | 7439-89-6 | 0.0005 | | 0.00000038 | |
| | Calcium | 7440-70-2 | 0.0020 | | 0.000000150 | |
| | Palladium | 7440-05-3 | 0.9900 | | 0.000074365 | |
| | Magnesium | 7439-95-4 | 0.0005 | | 0.00000038 | |
| **Solder Balls** | | | | | **0.2709** | **25.81%** |
| | Tin | 7440-31-5 | 63.00 | | 0.170667 | |
| | Lead | 7439-92-1 | 37.00 | | 0.100233 | |



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## Revision History

The following table shows the revision history for this document.

| Date | Revision | Revision |
| --- | --- | --- |
| 3/21/06 | 1.0 | Initial release. |
| 7/11/06 | 1.1 | 100% Material Declaration. |
| 9/21/06 | 1.2 | Updated component descriptions. |